

Product Change Notice (PCN)

Subject: Alternate leadframe material for assembly of the listed Intersil TSSOP packaged products

Publication Date: 5/3/2016

Effective Date: 8/2/2016

Revision Description:

Initial Release

Description of Change:

Alternate leadframe material for assembly of the listed Intersil TSSOP packaged products

Reason for Change:

This notice is to inform you that Intersil has qualified a change that standardizes the material and the assembly process for the listed TSSOP (Thin Shrink Small Outline Plastic) packaged products. The change implements the use of a higher quality copper leadframe material (old : C7025; new : C194). The change is necessary to maintain product manufacturability in support of customer delivery requirements.

The qualification plan is designed using JEDEC and other applicable industry standards to confirm form, fit, function and interchangeability of product. A summary of the qualification results are included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, etc.) will continue to be processed to previously establish conditions and systems.

Impact on fit, form, function, quality & reliability:

The change will have no impact on the form, fit, function, quality, reliability and environmental compliance of the devices.

Product Identification:

There will be no change in the external marking of the packaged parts. Product affected by this change is identifiable via Intersil's internal traceability system.

Qualification status: Completed, see attached

Sample availability: 5/3/2016

Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@INTERSIL.COM	Europe: PCN-EU@INTERSIL.COM	Japan: PCN-JP@INTERSIL.COM	Asia Pac: PCN-APAC@INTERSIL.COM

Appendix A - Affected Products List (see attached)

Product List

ICL3221CVZ	ICL3222ECVZ-TS2705	ICL3232EIV-16Z	ISL43144IVZ-TR5172
ICL3221CVZ-T	ICL3222EIVZ	ICL3232EIV-16Z-T	ISL43144IVZR5172
ICL3221CVZ-T7	ICL3222EIVZ-T	ICL3232EIV-16Z-T7A	ISL6722AAVZ
ICL3221CVZ-TS2705	ICL3222EIVZ-TS2490	ICL3232EIV-20Z	ISL6722AAVZ-T
ICL3221ECVZ	ICL3222IVZ	ICL3232EIV-20ZT	ISL83220ECVZ
ICL3221ECVZ-T	ICL3222IVZ-T	ICL3232IVZ	ISL83220ECVZ-T
ICL3221EIVZ	ICL3232CVZ	ICL3232IVZ-T	ISL83220ECVZ-TS2702
ICL3221EIVZ-T	ICL3232CVZ-T	ICL3232IVZ-T7A	ISL83220EIVZ
ICL3221EIVZ-T7A	ICL3232CVZ-TS2705	ISL43140IVZ	ISL83220EIVZ-T
ICL3221EMVZ	ICL3232ECV-16Z	ISL43140IVZ-T	ISL84521IVZ
ICL3221EMVZ-T	ICL3232ECV-16Z-T	ISL43141IVZ	ISL84521IVZ-T
ICL3222CVZ	ICL3232ECV-16Z-T7A	ISL43141IVZ-T	ISL84522IVZ
ICL3222CVZ-T	ICL3232ECV-20Z	ISL43143IVZ	ISL84522IVZ-T
ICL3222CVZ-TS2705	ICL3232ECV-20ZT	ISL43143IVZ-T	
ICL3222ECVZ	ICL3232EFV-16Z	ISL43144IVZ	
ICL3222ECVZ-T	ICL3232EFV-16Z-T	ISL43144IVZ-T	

Appendix B - Qualification Results (see attached)

Stress / Conditions	Duration	HIP6004ECVZ 20 Leads 6.50mm x 4.40mm TSSOP	ICL3222EIVZ-TS2490 20 Leads 6.50mm x 4.40mm TSSOP	ICL3232CVZ-T 16 Leads 5.00mm x 4.40mm TSSOP
Moisture Sensitivity Classification		N=44 Acc = 0 L3 PB Free	N=44 Acc = 0 L3 PB Free	N=44 Acc = 0 L1 PB Free
Unbiased HAST (u-HAST) +130°C / 85% RH	96 hours	N = 233 Acc = 0	N = 240 Acc = 0	N = 240 Acc = 0
Hot Temperature Storage (HTS) T _A = +150°C	1000 hours	N = 225 Acc = 0	N = 240 Acc = 0	N = 237 Acc = 0
Temperature Cycling (TC) -65°C / +150°C	500 cycles	N = 236 Acc = 0	N = 240 Acc = 0	N = 240 Acc = 0

Qualification completed and passed